

**AMENDMENTS TO THE CLAIMS**

Please amend the claims as follows:

1. (Currently Amended) A method for preventing contamination after plating a metal or an alloy on a surface of a substrate comprising:
  - a) providing a plating solution on the surface of the substrate;
  - b) electroplating or electrolysis plating the metal or alloy on the surface of the substrate; and,
  - c) introducing a second solution comprising a stabilizing agent, ~~the stabilizing agent comprising an acid which keeps metal or alloy ions in the plating solution, the stabilizing agent selected from the group consisting of citrate, acetate, EDTA, ammonia, hydrochloric acid and phosphoric acid.~~
2. (Original) Method according to claim 1, wherein in said introducing step (c) the stabilizing agent prevents formation of precipitated salts on the surface of the substrate.

Claims 3-6. (Canceled)

7. (Currently Amended) Method according to ~~claim 6~~ claim 1, wherein in said introducing step (c) ~~at least one of the aqueous solutions of the complexing~~ the stabilizing agent is introduced in the following concentrations:
  - Citrate in a preferred concentration of about 0.5 to about 1.0 mol/kg,
  - Acetate in a preferred concentration of about 0.5 mol/kg,
  - EDTA in a preferred concentration of about 0.2 to about 0.5 mol/kg, ~~and/or~~
  - Ammonia in a preferred concentration of about 0.1 to about 1.0 mol/kg
  - Hydrochloric Acid in a preferred concentration of about 0.1 mol/kg,
  - Hydrochloric Acid in a preferred concentration of about 0.01 mol/kg, or
  - Phosphoric Acid in a preferred concentration of about 0.1 mol/kg.

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8. (Canceled)
9. (Currently Amended) Method according to claim 1, wherein ~~the acid~~ the stabilizing agent does not form a low-soluble salt with the plated metals.

Claims 10-14. (Canceled)

15. (Original) Method according to claim 1, wherein the stabilizing agent is contained in the plating solution.
16. (Original) Method according to claim 1, wherein the substrate comprises a semiconductor wafer.

Claims 17-32. (Canceled)

33. (Currently Amended) In a method for plating a metal alloy on a surface of a substrate by electrolytic activity using a plating solution on the surface wherein the improvement comprises introducing a second solution comprising a stabilizing agent onto the substrate surface, the stabilizing agent ~~comprising an acid in order to keep~~ keeps metal alloy ions in the plating solution, the stabilizing agent selected from the group consisting of citrate, acetate, EDTA, ammonia, hydrochloric acid and phosphoric acid.
34. (Canceled)

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